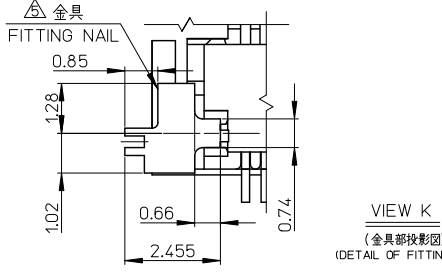
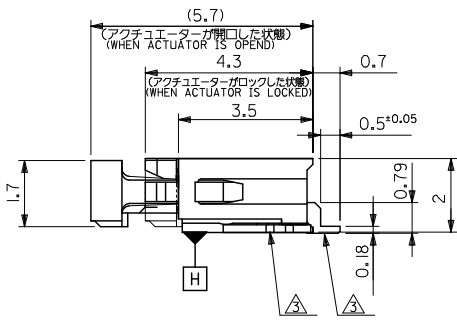
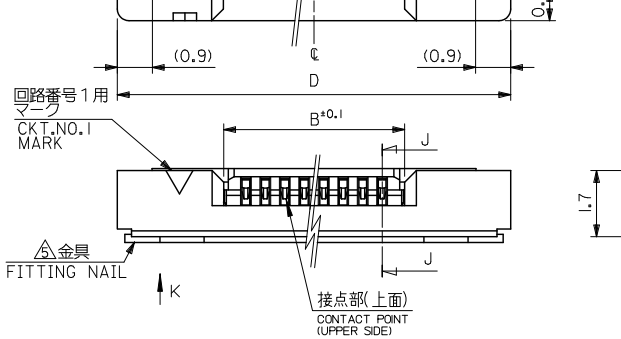
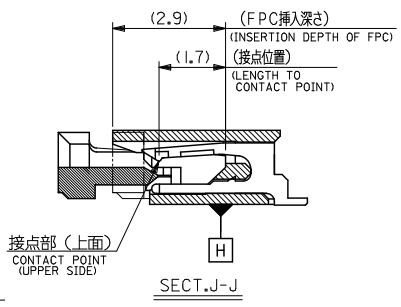
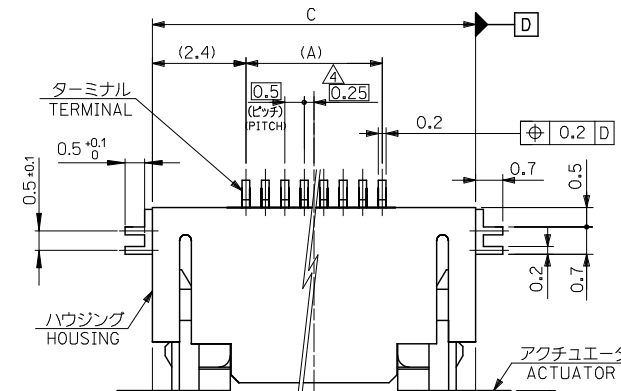


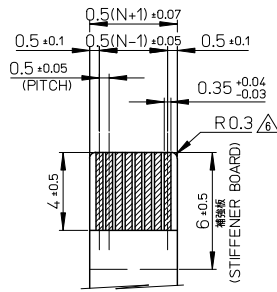
10 9 8 7 6 5 4 3 2 1



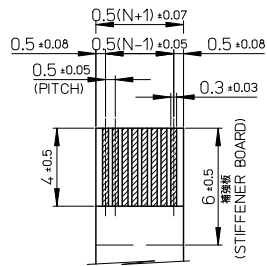
16.1	14.3	10.65	9.5	52745-2097	20
15.6	13.8	10.15	9	52745-1997	19
15.1	13.3	9.65	8.5	52745-1897	18
14.6	12.8	9.15	8	52745-1797	17
14.1	12.3	8.65	7.5	52745-1697	16
13.6	11.8	8.15	7	52745-1597	15
13.1	11.3	7.65	6.5	52745-1497	14
12.6	10.8	7.15	6	52745-1397	13
12.1	10.3	6.65	5.5	52745-1297	12
11.6	9.8	6.15	5	52745-1197	11
11.1	9.3	5.65	4.5	52745-1097	10
10.6	8.8	5.15	4	52745-0997	9
10.1	8.3	4.65	3.5	52745-0897	8
9.6	7.8	4.15	3	52745-0797	7
9.1	7.3	3.65	2.5	52745-0697	6
8.1	6.3	2.65	1.5	52745-0497	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-xx59

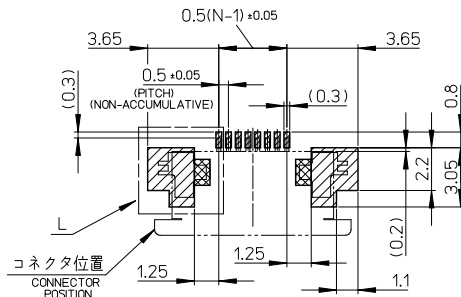
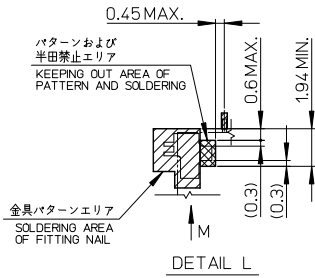
REVISED EC NO: J2011-0041 DRW:HYOSHINO 2010/07/08 CHK:KISHINOYAMA 2010/07/08 APPR:KIMORI KAWA 2010/07/16 DESCRIPTION (アクチュエーターが開口した状態) (アクチュエーターがロックした状態)	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DRAWN BY M.NABEI		DATE '05/02/14		TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING			
	ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY K.TOJO		DATE '05/02/14		MOLEX INCORPORATED			
	APPROVED BY N.UKI TA		DATE '05/02/14		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52745-050		SHEET NO. 1 OF 2



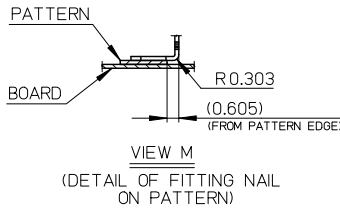
適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト  
 (マウント面)  
 RECOMMENDED P.C.BOARD  
 PATTERN DIMENSION(REF.)  
 (MOUNTING SIDE)



VIEW M  
 (DETAIL OF FITTING NAIL  
 ON PATTERN)

注記NOTES

1.使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白  
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒  
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK  
 ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)  
 TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING  
 金具: リン青銅、ニッケル下地金めっき (t=0.2)  
 FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART NO.52745-xx59 SHOULD BE LOCKED.

△ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。

△ MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H, UPPER DIRECTION: 0.1MAXIMUM, LOWER DIRECTION: 0.15 MAXIMUM

△ 偶数極に適用

△ APPLY FOR EVEN CIRCUIT.

△ ハターン剥離止め金具

△ FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

△ R0.3は、FPCの胴体部にかからないこと

△ R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7.ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。

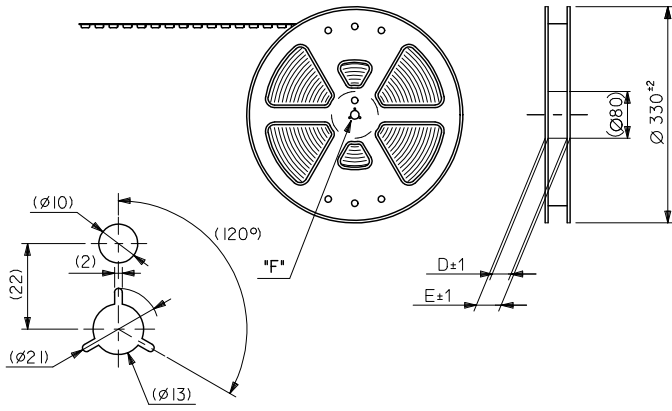
ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL : STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2011-0041 DRAWN BY: IDRWNYOSHINO CHECKED BY: CHYKOSHINOYAMA APPROVED BY: MORIKAWA	DESCRIPTION 02010/07/08 2010/07/08 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY M.NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING			
		10 OVER 30 UNDER	± ---	CHECKED BY K.TOJO	DATE '05/02/14	MOLEX INCORPORATED			
		30 OVER	± ---	APPROVED BY N.UKIITA	DATE '05/02/14	DOCUMENT NO. SD-52745-050			
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2			
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1

引き出し方向  
PULL OUT  
DIRECTION



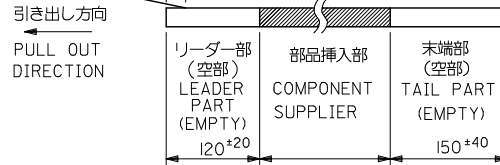
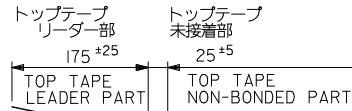
DETAIL "F"

5. 材料 キャリアテープ:ポリプロピレン (PP)  
 トップテープ:PET, PE, PEF  
 リール:ポリスチレン (PS) <リサイクル材を含む>  
 MATERIAL CARRIER TAPE:POLYPROPYLENE  
 TOP TAPE:PET,PE,PEF  
 REEL:POLYSTYRENE(PS)  
 <RECYCLE MATERIAL CONTAINED>

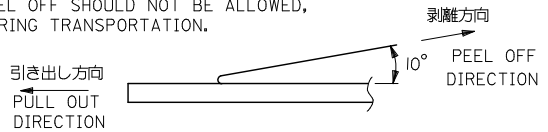
6. 本製品は 52745-\*\*90 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 52745-\*\*90  
 7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
 THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

注記 NOTES

- 製品番号 52745-\*\*59 の梱包状態はアクチュエータがロックした状態とする。  
 詳細寸法については図面 SD-52745-050 を参照下さい。  
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-\*\*59 SHOULD BE LOCKED  
 RE DETAILED DIMENSIONS,SEE SD-52745-050.
- 梱包数量:1000個/リール  
 NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

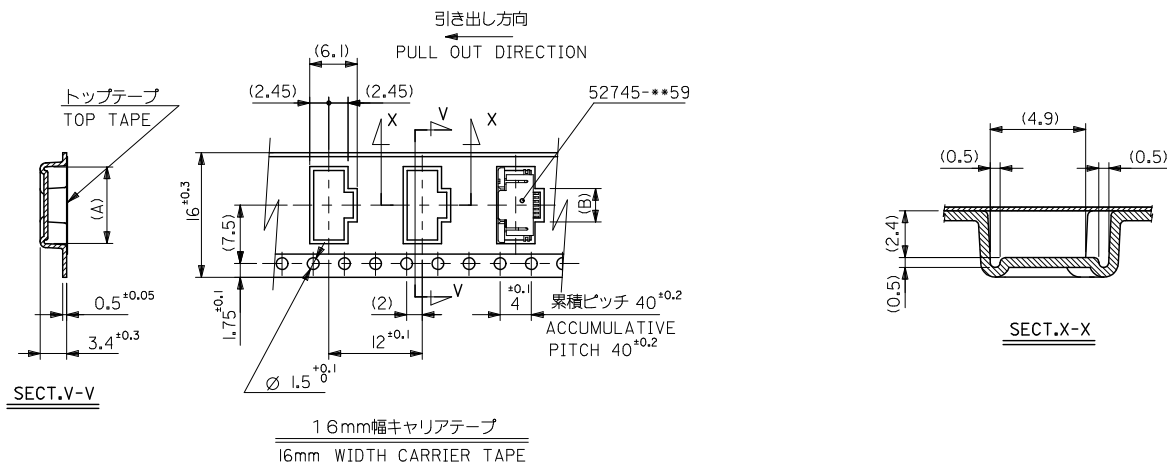


- トップテープの剥離強度: (剥離方向は下図参照)  
 0.1N~1.3N (10gf~130gf) 尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)  
 PEELING OFF FORCE OF TOP TAPE:  
 0.1N~1.3N(10gf~130gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION.



52745-\*\*97 MODEL NO.

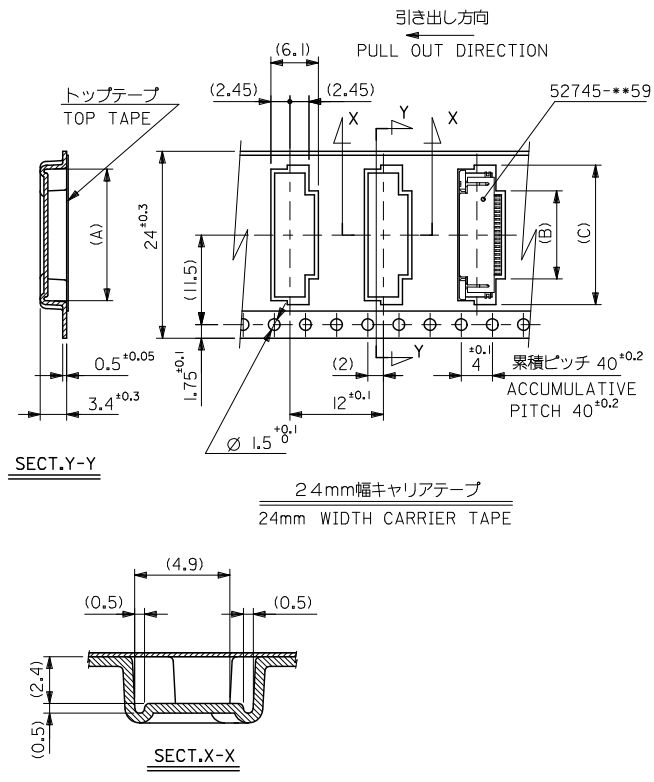
REVISED EC NO: J2009-2061 DRAWN BY DRYUNTKON 2009/05/20 CHKD BY CHYKHMATSUMOTO 2009/05/21 APPR. BY APPR. NIKITA 2009/05/21	DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±---	DRAWN BY M.NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	±---	CHECKED BY K.TOJO	DATE '05/02/14	MOLEX INCORPORATED			
		30 OVER	±---	APPROVED BY N.UKITA	DATE '05/02/14	DOCUMENT NO. SD-52745-051			
ANGULAR ±--- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 3		SIZE A3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



16	21.4	17.4	2.8	8.4	52745-0497	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-2061 DRAWN BY DRYUNIKON 2009/05/20 CHKD:HATSUNO 2009/05/21 APPR:NIKITA 2009/05/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±---	DRAWN BY M.NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	±---	CHECKED BY K.TOJO	DATE '05/02/14	APPROVED BY N.UKITA			
		30 OVER	±---	APPROVED BY N.UKITA	DATE '05/02/14	MATERIAL NO. SEE TABLE			
ANGULAR ±--- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52745-051		SHEET NO. 2 OF 3	

10 9 8 7 6 5 4 3 2 1



24	29.4	25.4	17.4	10.8	16.4	52745-2097	20
			16.9	10.3	15.9	-1997	19
			16.4	9.8	15.4	-1897	18
			15.9	9.3	14.9	-1797	17
			15.4	8.8	14.4	-1697	16
			14.9	8.3	13.9	-1597	15
			14.4	7.8	13.4	-1497	14
			13.9	7.3	12.9	-1397	13
			13.4	6.8	12.4	-1297	12
			12.9	6.3	11.9	-1197	11
			12.4	5.8	11.4	-1097	10
			11.9	5.3	10.9	-0997	9
			11.4	4.8	10.4	-0897	8
10.9	4.3	9.9	-0797	7			
10.4	3.8	9.4	52745-0697	6			
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-2061 DRAWN BY: CHYKHMATSUMOTO CHECKED BY: APPELNIKITA DATE: 2009/05/21 DATE: 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY M.NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±---	CHECKED BY K.TOJO	DATE '05/02/14	MOLEX INCORPORATED		
	30 OVER	±---	APPROVED BY N.UKITA	DATE '05/02/14	DOCUMENT NO. SD-52745-051	SHEET NO. 3 OF 3	
	ANGULAR	±--- °	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

tb\_frame\_A3\_J\_ME\_S  
Rev. E 2006/04/15

EN-02JA(021)